

FIG. 1

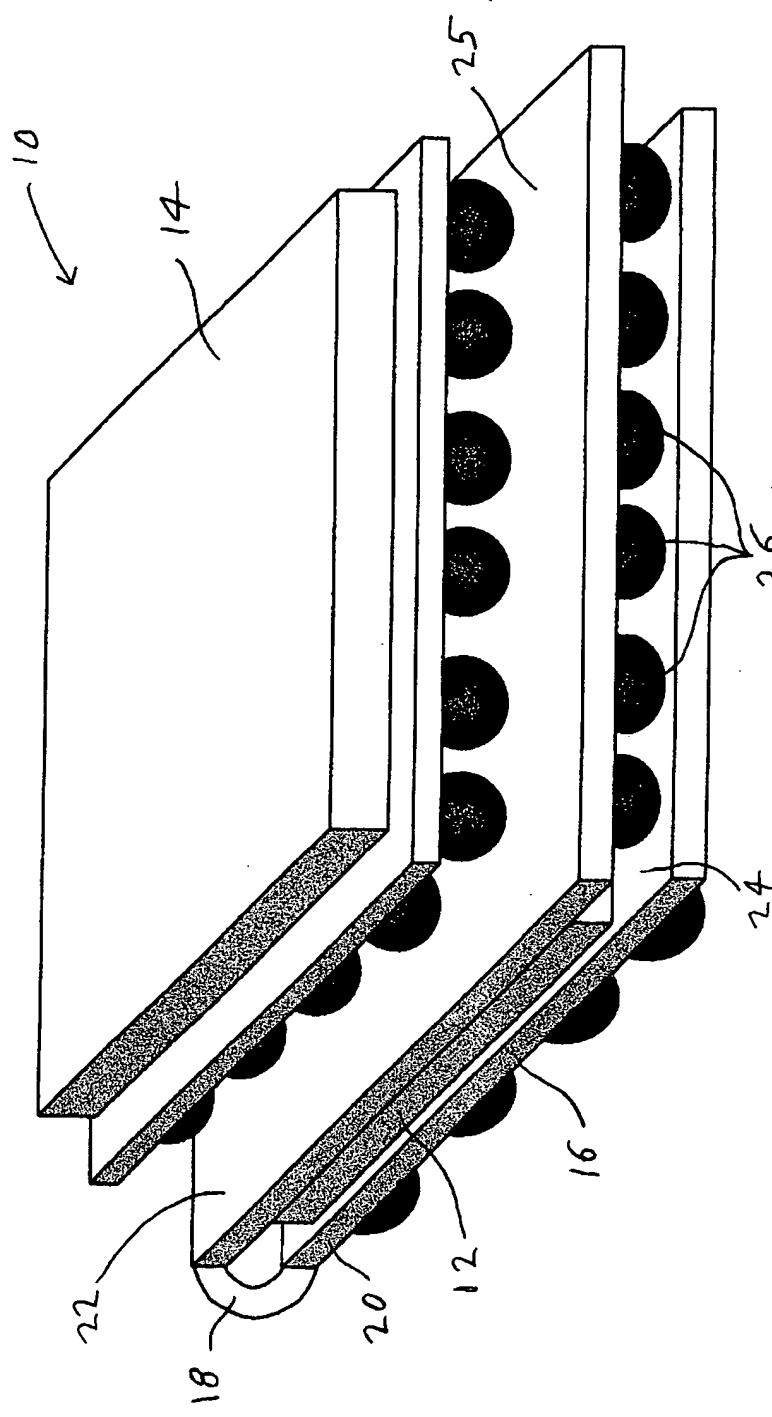


FIG. 2

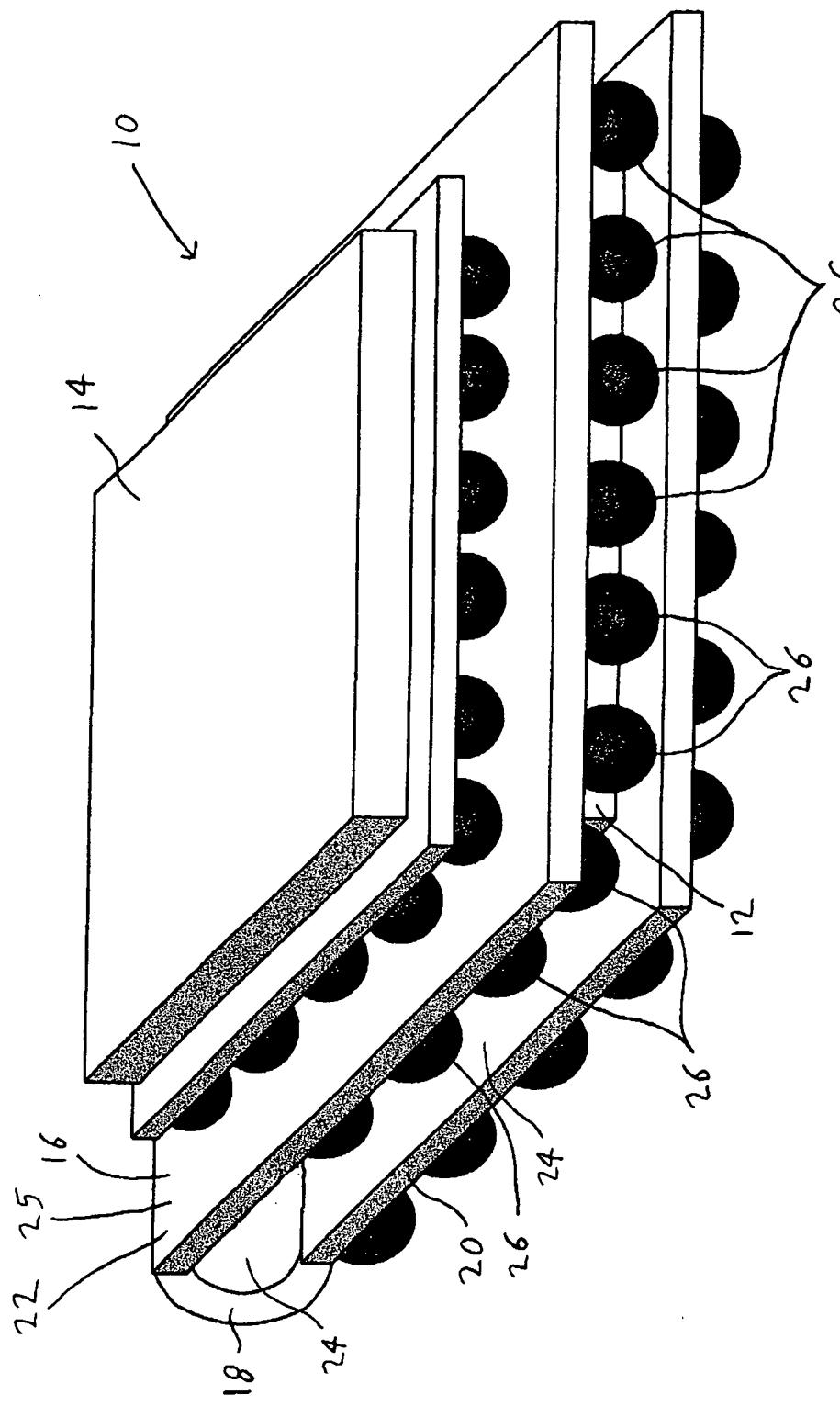


FIG. 3

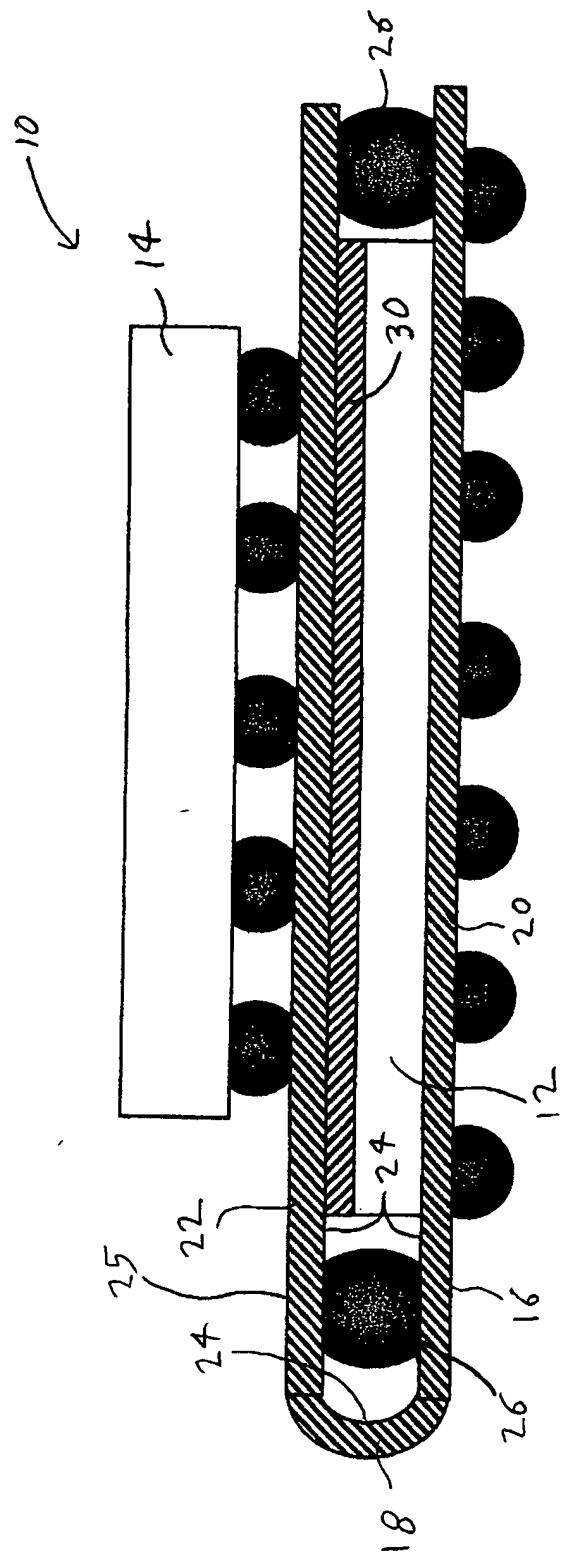


FIG. 4

50

securing a first die to a first section of an interposer, the interposer including a first conductor and a second conductor on a first surface of the interposer

- soldering the first die to the interposer

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folding the interposer to secure the first die to a second section of the interposer and to connect the first conductor to the second conductor to form a contact

- soldering the first conductor to the second conductor
- placing an adhesive on the first die and connecting the second section of the interposer to the adhesive
- forming a contact on an opposing side of the first die
- connecting each of the conductors to another conductor to form a plurality of contacts that extend from the first surface of the interposer between the first section and the second section
 - forming at least one contact on an opposing side of the first die
 - forming at least one contact on each side of the first die except for the one side of the first die
 - forming at least one contact on each side of the first die

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securing a second die to a second surface of the interposer such that the first and second dice are stacked one on top of another and electrically coupled by the interposer and the contact

- soldering the second die to the second surface of the interposer

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FIG. 5

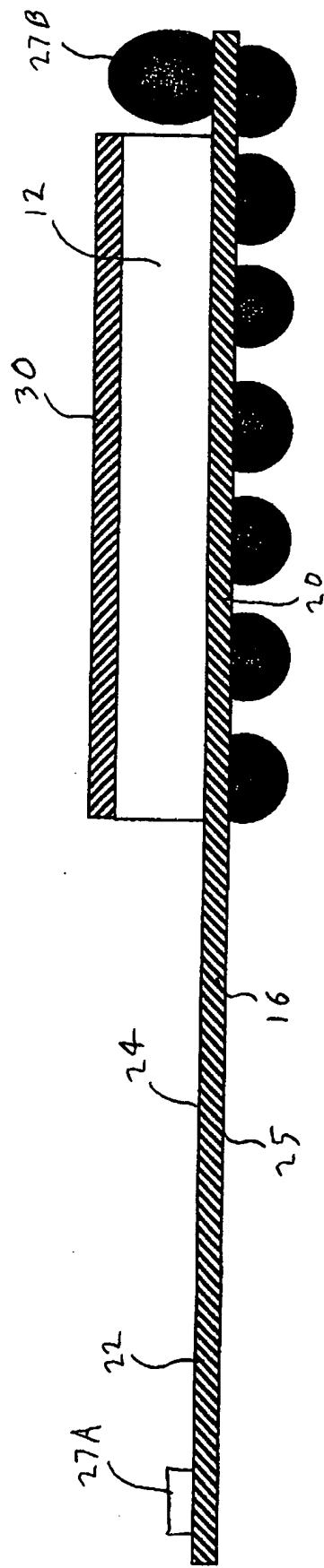


FIG. 6

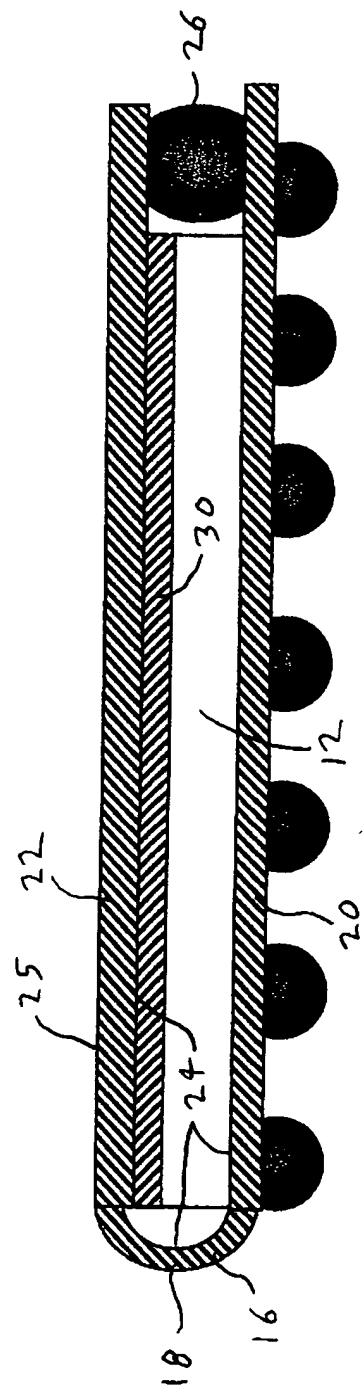


FIG. 7

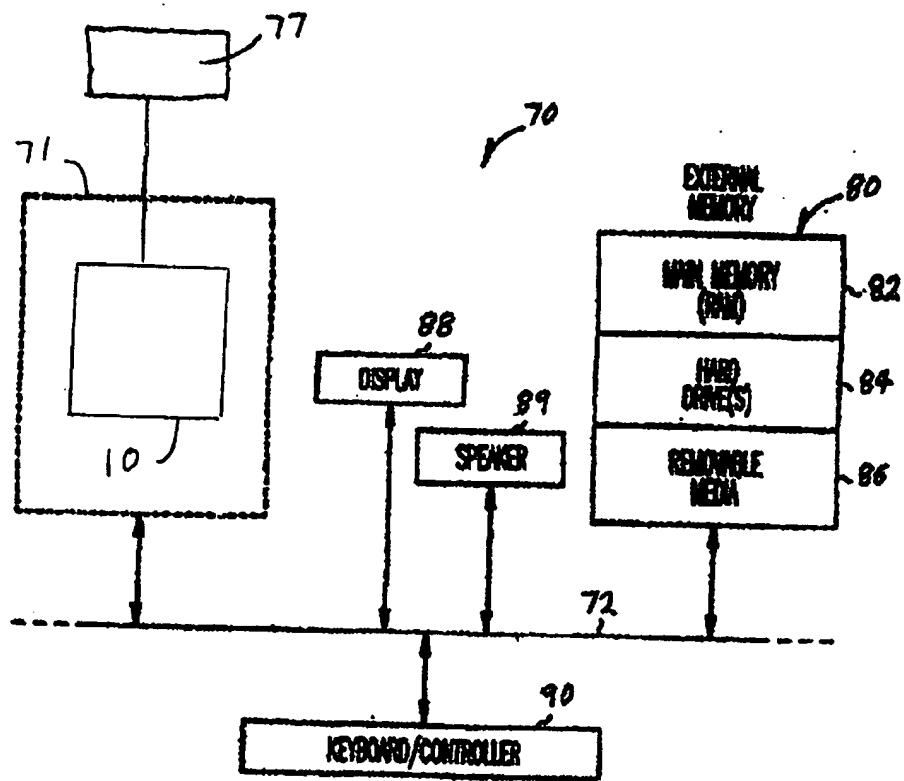


Fig. 8